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August 2009

# FSHDMI08 — Low-Voltage, Wide-Bandwidth, HDMI Switch with DDC and CEC Multiplexer

#### **Features**

- -25db Non-Adjacent Channel Crosstalk at 1.65Gbps
- Low Signal Loss: -1.5dBg attenuation at 1.65Gbps
- Isolation Ground Between Channels
- Fast Turn-on/off Time (< 6ns)
- 1.65Gbps Throughput
- 8kV ESD Protection
- Low Skew: Intra-pair <90ps, Inter-pair < 150ps
- Low Power Consumption: 1µA Maximum

## **Applications**

XGA and 720p DVI and HDMI Video Source Selection

### Description

The FSHDMI08 is a wide-bandwidth switch designed for routing HDMI link data, clock, and the relevant DDC and CEC control signals that support the data rate up to 1.65Gbps per channel for UXGA resolution. Applications include LCD TVs, DVD, set-top boxes, and notebook designs with multiple digital video interfaces.

This switch allows the passage of HDMI link signals with ultra-low non-adjacent channel crosstalk and ultra-low off isolation. This is critical to minimize ghost images between active video sources in video applications. The wide bandwidth of this switch allows the high-speed differential signal to pass through with minimal additive skew and phase jitter. The pinout supports an HDMI standard-A connector PCB layout.

#### **IMPORTANT NOTE:**

For additional information, please contact analogswitch@fairchildsemi.com.

## **Ordering Information**

Order Number	© Eco Status	Package Description	Packing Method
FSHDMI08MTDX	RoHS	56-Lead, Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide	Tape and Reel

For Fairchild's definition of Eco Status, please visit: <a href="http://www.fairchildsemi.com/company/green/rohs\_green.html">http://www.fairchildsemi.com/company/green/rohs\_green.html</a>.

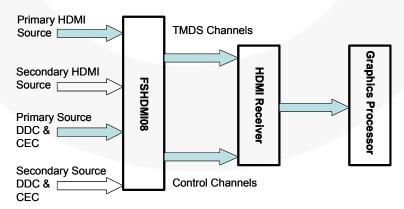


Figure 1. Single-Link HDMI Application

## **Functional Diagram**

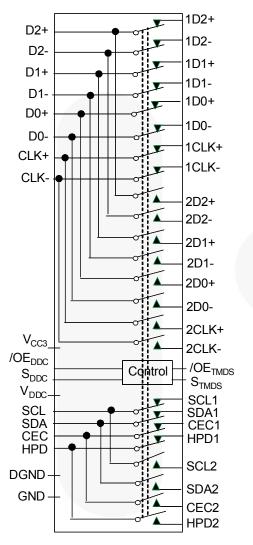


Figure 2. Functional Diagram

## **Pin Descriptions**

Pin	Name	Description  TMDS Data Channels		
1-4,6,7,11-14,16,17, 47,48,50,51,53,54	1Dn+, 1Dn-, 2Dn+, 2Dn-, Dn+, Dn-			
8,9,18,19,44,45	1CLK+, 1CLK-, 2CLK+, 2CLK-, CLK+, CLK-	TMDS Clock Channels		
24,28,33	HPD1, HPD2, HPD	Hot Plug Detects		
22,26,35	SCL1, SCL2, SCL	Serial Clock (DDC)		
23,27,34	SDA1, SDA2, SDA	Serial Data (DDC)		
21,25,36	CEC1, CEC2, CEC	Consumer Electronics Control (CEC)		
29	V <sub>DDC</sub>	DDC Power		
20,39,40,55,56	V <sub>CC3</sub>	TMDS Power		
30	DGND	DDC/CEC GND		
5,10,15,38,43,46,49,52	GND	GND		
32,42	S <sub>TMDS</sub> , S <sub>DDC</sub>	Select Pins (TMDS, DDC)		
31,41	/OE <sub>TMDS</sub> , /OE <sub>DDC</sub>	Output Enable (TMDS, DDC)		

#### **Pin Assignments** 56 V<sub>CC3</sub> 1D2+ 1D2-55 $V_{CC3}$ 1D1+ 54 D2+ 1D1-4 53 D2-**GND** 52 **GND** 1D0+ 6 51 D1+ 1D0-50 D1-1CLK+ 49 1CLK-48 D0+ **GND** 47 10 D0-2D2+ 46 **GND** 2D2-12 45 CLK+ 2D1+ CLK-2D1-43 GND 42 | S<sub>TMDS</sub> GND 15 41 /OE<sub>TMDS</sub> 2D0+ 2D0-40 $V_{CC3}$ 2CLK+ 18 39 $V_{CC3}$ 2CLK- 19 38 **GND** $V_{CC3}$ 20 37 **DGND** CEC1 21 36 CEC SCL1 22 35 SCL SDA1 34 SDA HPD1 33 HPD CEC2 25 32 $S_{DDC}$ SCL2 26 /OE<sub>DDC</sub> SDA2 27 30 **DGND** 29 HPD2 28 $V_{DDC}$

Figure 3. Pin Assignments

### **Truth Table**

S <sub>TMDS</sub> , S <sub>DDC</sub>	/OE <sub>TMDS</sub> ,	Function
Don't' Care	Logic Level HIGH	All Ports Disconnected (Hi-Z)
Logic Level LOW	Logic Level LOW	1Dn+/1Dn-=Dn+/Dn-; 1CLK+/ 1CLK-=CLK+/CLK-; HPD1=HPD; SCL1=SCL; SDA1=SDA; CEC1=CEC
Logic Level HIGH	Logic Level LOW	2Dn+/2Dn-=Dn+/Dn-; 2CLK+/ 2CLK-=CLK+/CLK-; HPD2=HPD; SCL2=SCL; SDA2=SDA; CEC2=CEC

## **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter			Min.	Max.	Unit
V <sub>CC3</sub>	Supply Voltage – TMDS	S Channels		-0.5	4.6	V
$V_{DDC}$	Supply Voltage – 5V DI	С		-0.5	6.0	V
V <sub>SWTMDS</sub> <sup>(1)</sup>	Switch I/O Voltage	1Dn+, 1Dn-, 2Dn+, 2Dn 1CLK-, 2CLK+, 2CLK-,	, , , , ,	-0.5	V <sub>CC3</sub> + 0.3	٧
V <sub>SWDDC</sub> <sup>(1)</sup>	Switch I/O Voltage	HPD1, HPD2, HPD, SO SDA1, SDA2, SDA, CE		-0.5	V <sub>DDC</sub> + 0.3	٧
V <sub>CNTRLT</sub> <sup>(1)</sup>	Control Input Voltage	S <sub>TMDS</sub> , /OE <sub>TMDS</sub>		-0.5	4.6	V
V <sub>CNTRLD</sub> <sup>(1)</sup>	Control Input Voltage	S <sub>DDC</sub> , /OE <sub>DDC</sub>		-0.5	6.0	V
I <sub>IK</sub>	Input Clamp Diode Current			-50	mA	
I <sub>SW</sub>	Switch I/O Current (Cor	ntinuous)			128	mA
T <sub>STG</sub>	Storage Temperature Range		-65	+150	°C	
TJ	Maximum Junction Tem	Maximum Junction Temperature			+150	°C
T <sub>L</sub>	Lead Temperature (Soldering, 10 Seconds)			+260	°C	
	Human Body Model (JEDEC: JESD22-A114)  I/O to GND All Other Pi		I/O to GND	1	8.0	
ESD			All Other Pins		2.5	kV
	Charged Device Model	(JEDEC: JESD22-C101	)		2.0	

#### Note:

## **Recommended Operating Conditions**

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Min.	Max.	Unit
V <sub>CC3</sub>	TMDS Supply Voltage – 3V	3.0	4.3	V
$V_{DDC}$	DDC Supply Voltage	3.0	5.5	V
V <sub>CNTRLT</sub>	Control Input Voltage – S <sub>TMDS</sub> , /OE <sub>TMDS</sub>	0	V <sub>CC3</sub>	V
V <sub>CNTRLD</sub>	Control Input Voltage – S <sub>DDC</sub> , /OE <sub>DDC</sub>	0	$V_{DDC}$	V
$V_{SWTMDS}$	Switch I/O Voltage for HDMI path	V <sub>CC3</sub> – 0.6	$V_{CC3}$	V
$V_{SWDDC}$	Switch I/O Voltage for DDC path	0	$V_{DDC}$	V
T <sub>A</sub>	Operating Temperature	-40	+85	°C
θЈА	Thermal Resistance (Free Air)		+80	°C/W

The input and output negative ratings may be exceeded if the input and output diode current ratings are observed.

## **DC Electrical Characteristics**

All typical values are for  $V_{CC3}$ =3.3V and  $V_{DDC}$ =5.0V at 25°C unless otherwise specified.

Symbol	Parameter V <sub>CC3</sub> / V	V (V 00	()/ ()/) Conditions	T <sub>A</sub> =- 40°C to +85°C			l lasit
Symbol		V <sub>CC3</sub> / V <sub>DDC</sub> (V)	Conditions	Min.	Тур.	Max.	Unit
V <sub>IK</sub>	Clamp Diode Voltage	V <sub>CC3</sub> =3.0 V <sub>DDC</sub> =5.0	I <sub>IN</sub> =-18mA			-1.2	٧
V <sub>IH</sub>	Control Input Voltage High	V <sub>CC3</sub> =3.0 to 3.6 V <sub>DDC</sub> =3.0 to 5.5		2			٧
V <sub>IL</sub>	Control Input Voltage Low	V <sub>CC3</sub> =3.0 to 3.6 V <sub>DDC</sub> =3.0 to 5.5				0.8	V
I <sub>OZTMDS</sub>	Off State Leakage TMDS Channels	V <sub>CC3</sub> =3.6 V <sub>DDC</sub> =5.5	$0 \le V_{SWTMDS} \le V_{CC3}$ Figure 5	-1		1	μΑ
I <sub>OZDDC</sub>	Off State Leakage DDC/CEC Channels	V <sub>CC3</sub> =3.6 V <sub>DDC</sub> =5.5	$0 \le V_{SWDDC} \le V_{DDC}$ Figure 5	-5		5	μΑ
I <sub>INTMDS</sub>	Control Input Leakage (S <sub>TMDS</sub> , /OE <sub>TMDS</sub> )	V <sub>CC3</sub> =3.6 V <sub>DDC</sub> =5.5	V <sub>SWDDC</sub> =0 to V <sub>CC3</sub>	-1		1	μA
I <sub>INDDC</sub>	Control Input Leakage (S <sub>DDC</sub> , /OE <sub>DDC</sub> )	V <sub>CC3</sub> =3.6 V <sub>DDC</sub> =5.5	V <sub>SWDDC</sub> =0 to V <sub>DDC</sub>	-1		1	μA
I <sub>CC3</sub>	Quiescent Supply Current -TMDS	V <sub>CC3</sub> =3.6 V <sub>DDC</sub> =5.5	$V_{SWTMDS}=V_{CC3}-0.6$ or $V_{CC3}$ , $I_{OUT}=0$			2	μA
I <sub>DDC</sub>	Quiescent Supply Current -DDC	V <sub>CC3</sub> =3.6 V <sub>DDC</sub> =5.5	$V_{SWDDC}$ =0 or $V_{DDC}$ , $I_{OUT}$ =0	1		2	μA
ΔІССТЗ	Increase in I <sub>CC3</sub>	V <sub>CC3</sub> =3.6 V <sub>CC5</sub> =5.5	One input at 3.0V; Other inputs at V <sub>CC3</sub> - 0.6 or V <sub>CC3</sub>			100	μΑ
Δl <sub>CCTD</sub>	Increase in I <sub>DDC</sub>	V <sub>CC3</sub> =3.6 V <sub>CC5</sub> =5.5	One input at 3.0V; Other inputs at V <sub>DDC</sub>			15	μΑ

## **AC Electrical Characteristics**

All typical values are for  $V_{CC3}$ =3.3V and  $V_{DDC}$ =5.0V at 25°C unless otherwise specified.

Symbol Baramatar		V/V (A)	Conditions	T <sub>A</sub> =- 40°C to +85°C			11:4:4
Symbol	Parameter	V <sub>CC3</sub> / V <sub>DDC</sub> (V)	Conditions	Min.	Тур.	Max.	Unit
TMDS Chan	nels						•
t <sub>ONTMDS</sub>	Turn-On Time S, /OE to Output	V <sub>CC3</sub> =3.0 to 3.6 V <sub>DDC</sub> =5.0	$V_{SWTMDS}=V_{CC3}$ -0.5, $R_{PU}=50\Omega, C_L=5pf$		4	6	
	3,70L to Output	VDDC = 3.0	Figure 6, Figure 7				ns
t <sub>OFFTMDS</sub>	Turn-Off Time S to Output	V <sub>CC3</sub> =3.0 to 3.6 V <sub>DDC</sub> =5.0	$V_{SWTMDS}=V_{CC3}$ -0.5, $R_{PU}=50\Omega$ , $C_L=5pf$		2	4	115
	o to output	VDDC -0.0	Figure 6, Figure 7				
t <sub>BBM-TMDS</sub>	Break-Before-Make	V <sub>CC3</sub> =3.0 to 3.6 V <sub>DDC</sub> =5.0	$V_{SWTMDS}=V_{CC3}$ -0.5, $R_{PU}=50\Omega$ , $C_L=5pf$	1			ns
		1880 010	Figure 15				
$t_{pd}$ ( $t_{pLH}$ , $t_{pHL}$ )	Switch Propagation Delay <sup>(2)</sup>	V <sub>CC3</sub> =3.0 to 3.6 V <sub>DDC</sub> =5.0	$R_{PU}$ =50Ω, $C_{L}$ =5pf Figure 14			400	ps
t <sub>jitter</sub>	Total Jitter (DJ+RJ)	V <sub>CC3</sub> =3.0 to 3.6 V <sub>DDC</sub> =5.0	f=165MHz clock with 50% duty cycle, R <sub>PU</sub> =50Ω, C <sub>L</sub> =5pf			90	ps
t <sub>ratio</sub>	Duty Cycle Ratio	V <sub>CC3</sub> =3.0 to 3.6 V <sub>DDC</sub> =5.0	Figure 14  f=165MHz clock with 50% duty cycle, R <sub>PU</sub> =50Ω, C <sub>L</sub> =5pf Figure 14	40	50	60	%
t <sub>sĸ1</sub>	Intra-Pair Skew (TMDS Cn+ to Cn-)	V <sub>CC3</sub> =3.0 to 3.6 V <sub>DDC</sub> =5.0	f=1.65Gbps, $2^{23}$ -1 PRBS, $R_{PU}$ =50Ω, $C_L$ =5pf Figure 14		55	100	ps
t <sub>SK2</sub>	Inter-Pair Skew (Between any two TMDS switch pair paths)	V <sub>CC3</sub> =3.0 to 3.6 V <sub>DDC</sub> =5.0	f=1.65Gbps, 2 <sup>23</sup> -1 PRBS, R <sub>PU</sub> =50Ω, C <sub>L</sub> =5pf Figure 14		90	160	ps
	Off-Isolation	V <sub>CC3</sub> =3.0 to 3.6 V <sub>DDC</sub> =5.0	$R_T$ =50 $\Omega$ , f=370MHz Figure 10	-30			
OIRR <sub>TMDS</sub>	(TMDS Channels)	V <sub>CC3</sub> =3.0 to 3.6 V <sub>DDC</sub> =5.0	$R_T$ =50 $\Omega$ , f=825MHz Figure 10	-25			dB
Xtalk <sub>TMDS</sub> Crosstalk	Non-Adjacent Channel	V <sub>CC3</sub> =3.0 to 3.6 V <sub>DDC</sub> =5.0	$R_T$ =50 $\Omega$ , f=370MHz Figure 11	-25			ЧD
	(TMDS Channels)	V <sub>CC3</sub> =3.0 to 3.6 V <sub>DDC</sub> =5.0	$R_T$ =50 $\Omega$ , f=825MHz Figure 11	-20			dB
f <sub>max</sub>	Maximum Throughput <sup>(2)</sup>	V <sub>CC3</sub> =3.3 V <sub>DDC</sub> =5.0			1.65		Gbps
Control Cha	nnels - DDC / CEC						
tonddc	Turn-On Time; S <sub>DDC</sub> , /OE <sub>DDC</sub> to Output	V <sub>CC3</sub> =3.3 V <sub>DDC</sub> =3.0 to 5.5	$V_{SWDDC}$ =2V, $R_{DDC}$ =1k $\Omega$ , $C_L$ =5pf			28	ns
t <sub>OFFDDC</sub>	Turn-Off Time; S <sub>DDC</sub> , /OE <sub>DDC</sub> to Output	V <sub>CC3</sub> =3.3 V <sub>DDC</sub> =3.0 to 5.5	$V_{SWDDC}$ =2V, $R_L$ =1k $\Omega$ , $C_L$ =5pf			24	ns

### Note:

2. Guaranteed by characterization, not production tested.

### **Test Diagrams**

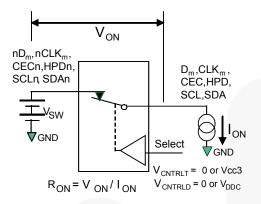
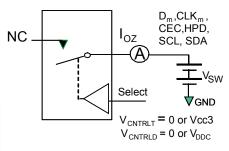


Figure 4. On Resistance



Each switch port is tested separately.

Figure 5. Off Leakage

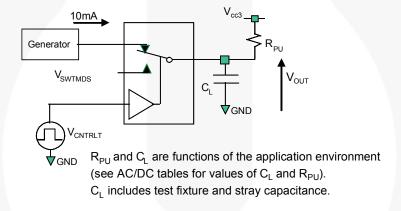


Figure 6. TMDS Test Circuit Load

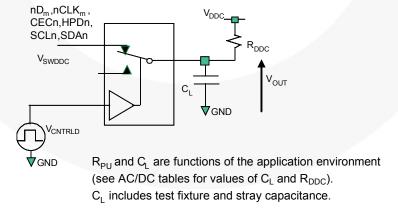
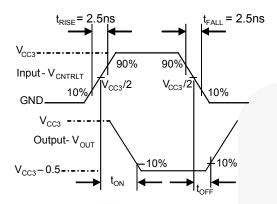


Figure 7. DDC Test Circuit Load

## **Test Diagrams**



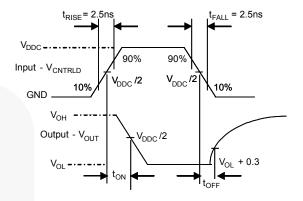


Figure 8. Turn-on / Turn-off Waveforms

Figure 9. DDC Turn-on / Turn-off Waveforms

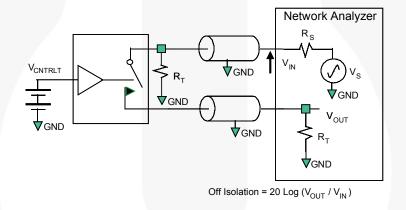


Figure 10. Channel Off Isolation

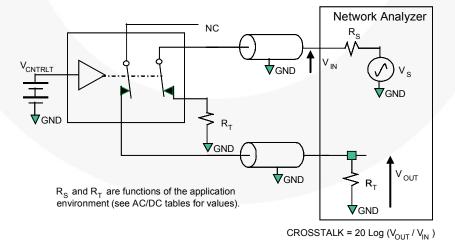


Figure 11. Non-Adjacent Channel-to-Channel Crosstalk

## **Test Diagrams**

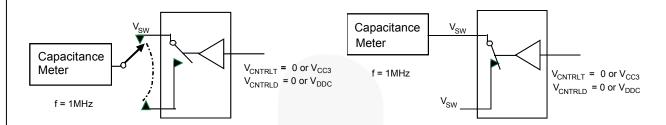


Figure 12. Channel Off Capacitance

Figure 13. Channel On Capacitance

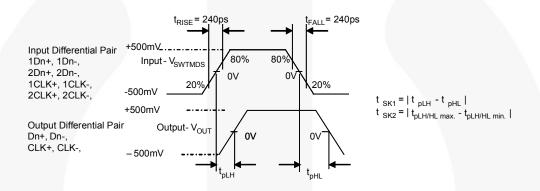


Figure 14. Intra- and Inter-Pair Skew tpd

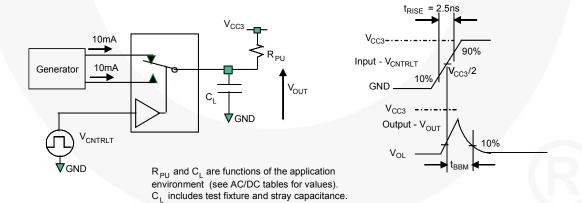


Figure 15. Break Before Make

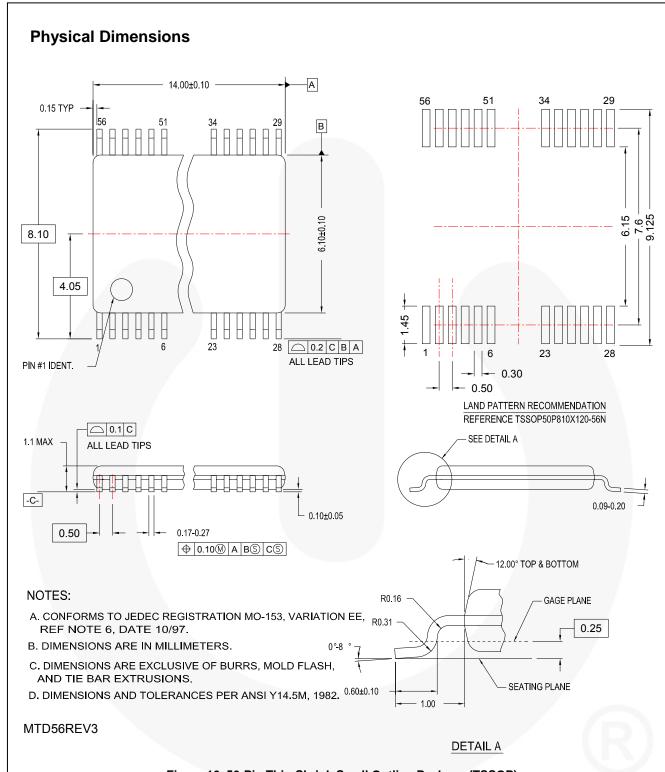


Figure 16. 56-Pin Thin-Shrink Small Outline Package (TSSOP)

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#### Definition of Terms

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